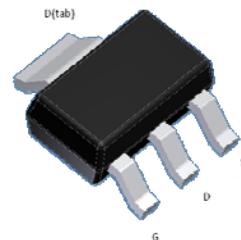
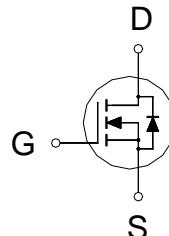


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV _{DSS}	200V
R _{DSON} (MAX.)	0.5Ω
I _D	1.6A



UIS, 100% Tested

Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V _{GS}	±30	V
Continuous Drain Current	T _C = 25 °C	I _D	1.6	A
	T _C = 100 °C		1	
Pulsed Drain Current ¹		I _{DM}	6.4	
Power Dissipation	T _C = 25 °C	P _D	6.25	W
	T _C = 100 °C		2.5	
Operating Junction & Storage Temperature Range		T _j , T _{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R _{θJC}	20	20	°C / W
Junction-to-Ambient	R _{θJA}		150	

¹Pulse width limited by maximum junction temperature.

²Duty cycle ≤ 1%

ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	200			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	3.0	4.0	5.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 30\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 160\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 130\text{V}, V_{\text{GS}} = 0\text{V}, T_j = 125^\circ\text{C}$			25	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = 5\text{V}, V_{\text{GS}} = 10\text{V}$	1.6			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_D = 0.8\text{A}$		0.4	0.5	Ω
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 0.8\text{A}$		2		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1\text{MHz}$		803		pF
Output Capacitance	C_{oss}			19		
Reverse Transfer Capacitance	C_{rss}			16		
Total Gate Charge ^{1,2}	Q_g	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 0.8\text{A}$		21.3		nC
Gate-Source Charge ^{1,2}	Q_{gs}			2.9		
Gate-Drain Charge ^{1,2}	Q_{gd}			6		
Turn-On Delay Time ^{1,2}	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 100\text{V}, I_D = 0.5\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GS}} = 6\Omega$		20		nS
Rise Time ^{1,2}	t_r			60		
Turn-Off Delay Time ^{1,2}	$t_{\text{d}(\text{off})}$			20		
Fall Time ^{1,2}	t_f			50		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_c = 25^\circ\text{C}$)						
Continuous Current	I_S				1.6	A
Pulsed Current ³	I_{SM}				6.4	
Forward Voltage ¹	V_{SD}	$I_F = I_S, V_{\text{GS}} = 0\text{V}$			1.5	V

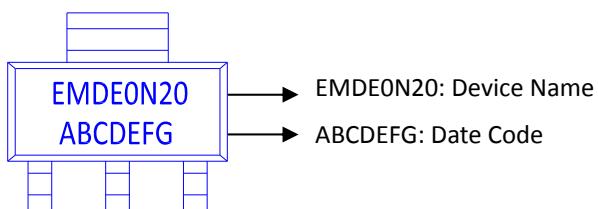
¹Pulse test : Pulse Width $\leq 300 \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

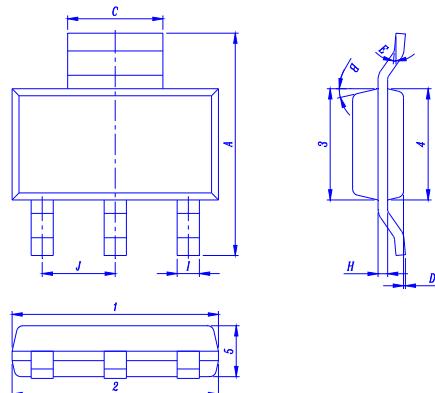
³Pulse width limited by maximum junction temperature.

Ordering & Marking Information:

Device Name: EMDEON20Q for SOT-223



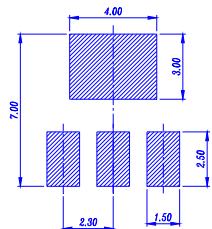
Outline Drawing



Dimension in mm

Dimension	A	C	D	E	I	H	B	J	1	2	3	4	5
Min.	6.70	2.90	0.02	0°	0.60	0.25			6.30	63.0	3.30	3.30	1.40
Typ.								13°	2.30				
Max.	7.30	3.10	0.10	10°	0.80	0.35			6.70	6.70	3.70	3.70	1.80

Recommended minimum pads



TYPICAL CHARACTERISTICS

